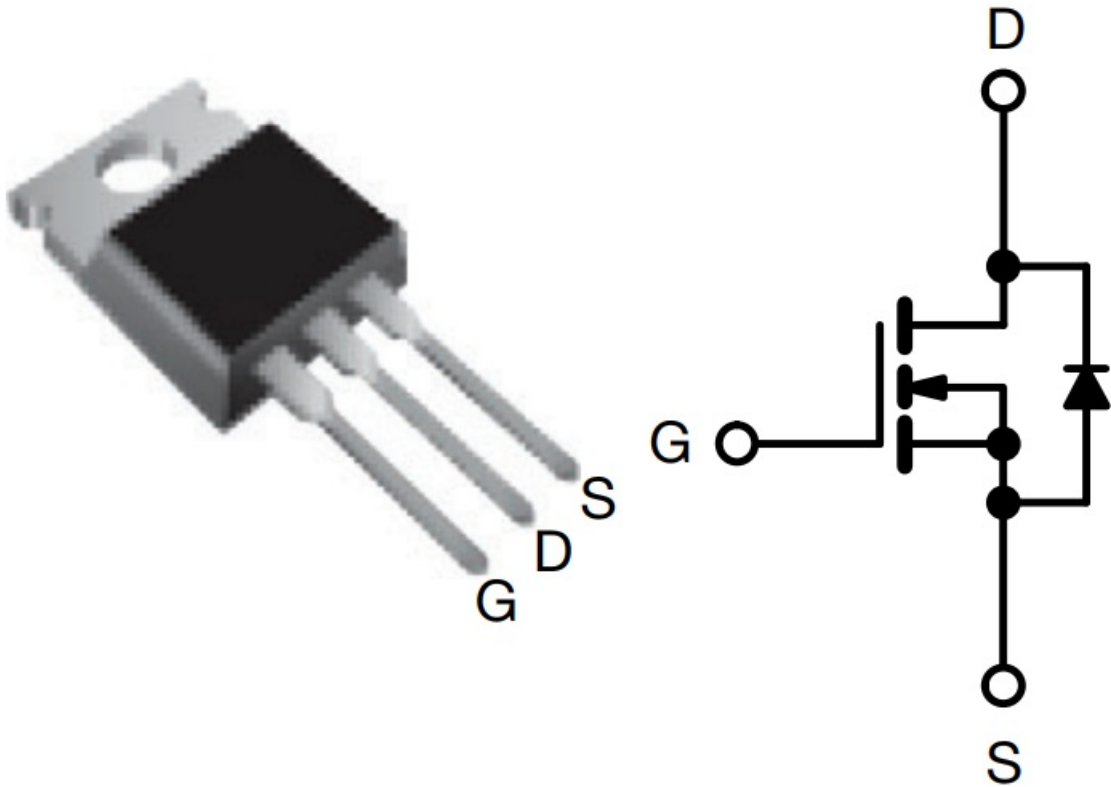


VISHAY IRF830B D Series Power MOSFET Owner’s Manual

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VISHAY IRF830B D Series Power MOSFET



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FEATURES

- Optimal design
 - Low area specific on-resistance
 - Low input capacitance (Ciss)
 - Reduced capacitive switching losses
 - High body diode ruggedness
 - Avalanche energy rated (UIS)
- Optimal efficiency and operation
 - Low cost
 - Simple gate drive circuitry
 - Low figure-of-merit (FOM): $R_{on} \times Q_g$
 - Fast switching
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Consumer electronics
 - Displays (LCD or plasma TV)
- Server and telecom power supplies
 - SMPS
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- Battery chargers

PRODUCT SUMMARY		
V _{DS} (V) at T _J max.	550	
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V	1.5
Q _g max. (nC)	20	
Q _{gs} (nC)	3	
Q _{gd} (nC)	5	
Configuration	Single	

ORDERING INFORMATION	
Package	TO-220AB
Lead (Pb)-free	IRF830BPbF
Lead (Pb)-free and halogen-free	IRF830BPbF-BE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			VDS	500	V
Gate-source Voltage			VGS	± 30	
Gate-source voltage AC (f > 1 Hz)				30	
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 25 °C	I _D	5.3	A
		T _C = 100 °C		3.4	
Pulsed drain current a			IDM	10	
Linear derating factor				0.83	W/°C
Single pulse avalanche energy b			EAS	28.8	mJ
Maximum power dissipation			P _D	104	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	T _J = 125 °C		dV/dt	24	V/ns
Reverse diode dV/dt d		0.28			
Soldering recommendations (peak temperature) c	For 10 s			300	°C

Notes

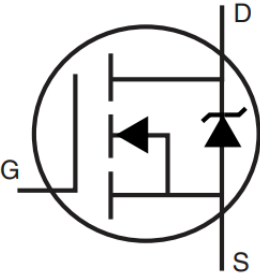
- **a.** Repetitive rating; pulse width limited by maximum junction temperature
- **b.** V_{DD} = 50 V, starting $T_J = 25\text{ }^{\circ}\text{C}$, L = 2.3 mH, R_g = 25 Ω , I_{AS} = 5 A
- **c.** 1.6 mm from case
- **d.** $ISD \leq ID$, starting $T_J = 25\text{ }^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R _{thJA}	–	62	$^{\circ}\text{C}/\text{W}$
Maximum junction-to-case (drain)	R _{thJC}	–	1.2	

SPECIFICATIONS

SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		500	—	—	V
V _{DS} temperature coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 250 μA		—	0.58	—	V/°C
Gate-source threshold voltage (N)	V _{GS} (th)	V _{DS} = V _{GS} , I _D = 250 μA		3	—	5	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 30 V		—	—	± 10 0	nA
Zero gate boltage drain current	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		—	—	1	μA
		V _{DS} = 400 V, V _{GS} = 0 V, T _J = 125 °C		—	—	10	
Drain-source on-state resistance	R _{DS} (on)	V _{GS} = 10 V	I _D = 2.5 A	—	1.2	1.5	Ω
Forward transconductance a	g _{fs}	V _{DS} = 20 V, I _D = 2.5 A		—	1.8	—	S
Dynamic							
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 100 V, f = 1 MHz		—	325	—	pF
Output capacitance	C _{oss}			—	34	—	
Reverse transfer capacitance	C _{rss}			—	6	—	
Effective output capacitance, energy related b	C _o (er)	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		—	31	—	
Effective output capacitance, time related c	C _o (tr)			—	41	—	
Total gate charge	Q _g	V _{GS} = 10 V	I _D = 2.5 A, V _{DS} = 400 V	—	10	20	nC
Gate-source charge	Q _{gs}			—	3	—	
Gate-drain charge	Q _{gd}			—	5	—	
Turn-on delay time	t _d (on)	V _{DD} = 400 V, I _D = 2.5 A R _g = 9.1		—	12	24	
Rise time	t _r			—	11	22	

Turn-off delay time	$t_{d(off)}$	$U, V_{GS} = 10 \text{ V}$	–	14	28	ns
Fall time	t_f		–	11	22	
Gate input resistance	R_g	$f = 1 \text{ MHz, open drain}$	0.8	1.7	3.4	\dot{U}
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	MOSFET symbol showing the integral reverse P – N junction diode 	–	–	5	A
Pulsed diode forward current	I_{SM}		–	–	20	
Diode forward voltage	V_{SD}	$T_J = 25 \text{ °C, } I_S = 4 \text{ A, } V_{GS} = 0 \text{ V}$	–	–	1.2	V
Reverse recovery time	t_{rr}	$T_J = 25 \text{ °C, } I_F = I_S = 2.5 \text{ A, } di/dt = 100 \text{ A/}\mu\text{s, } V_R = 20 \text{ V}$	–	320	–	ns
Reverse recovery charge	Q_{rr}		–	1.2	–	μC
Reverse recovery current	I_{RRM}		–	8	–	A

TYPICAL CHARACTERISTICS

(25 °C, unless otherwise noted)

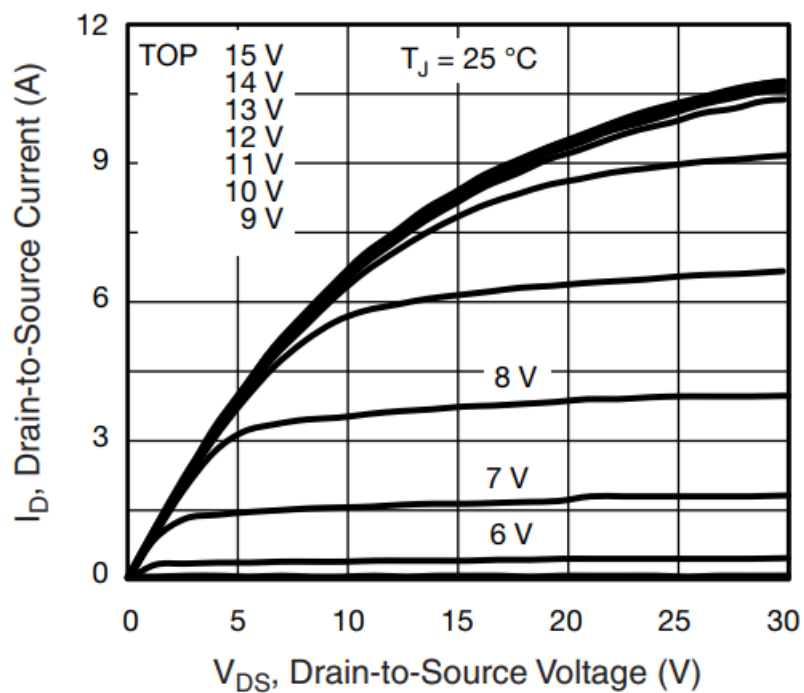


Fig. 1 - Typical Output Characteristics

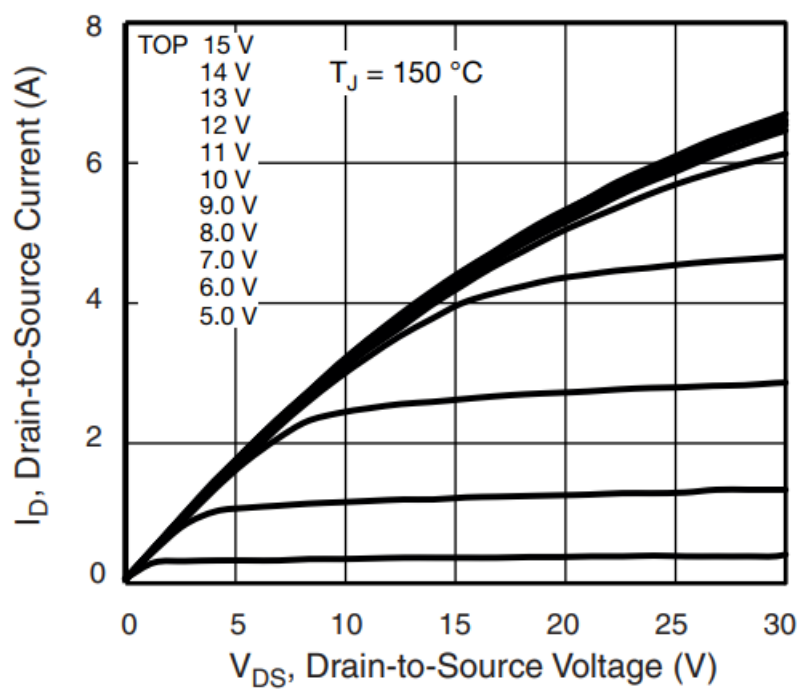


Fig. 2 - Typical Output Characteristics

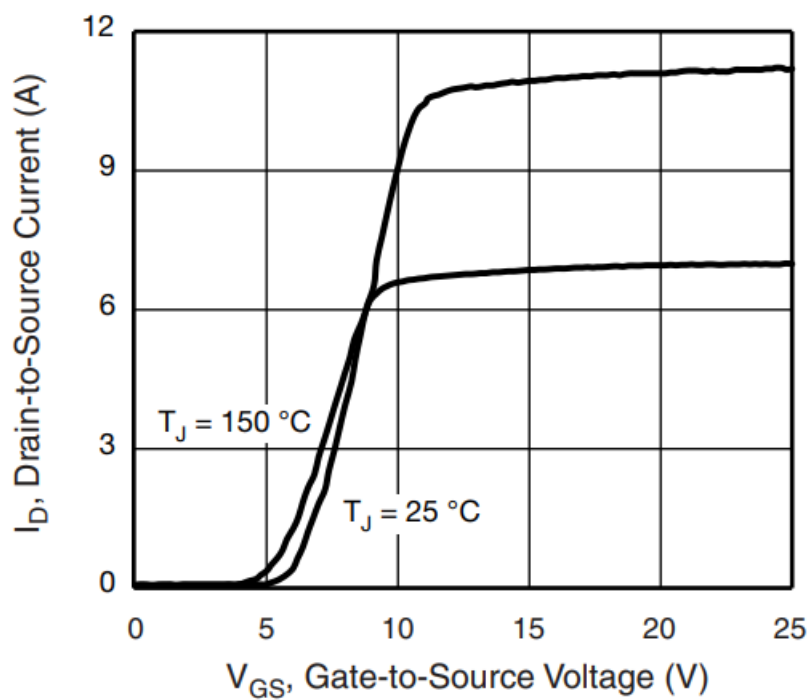


Fig. 3 - Typical Transfer Characteristics

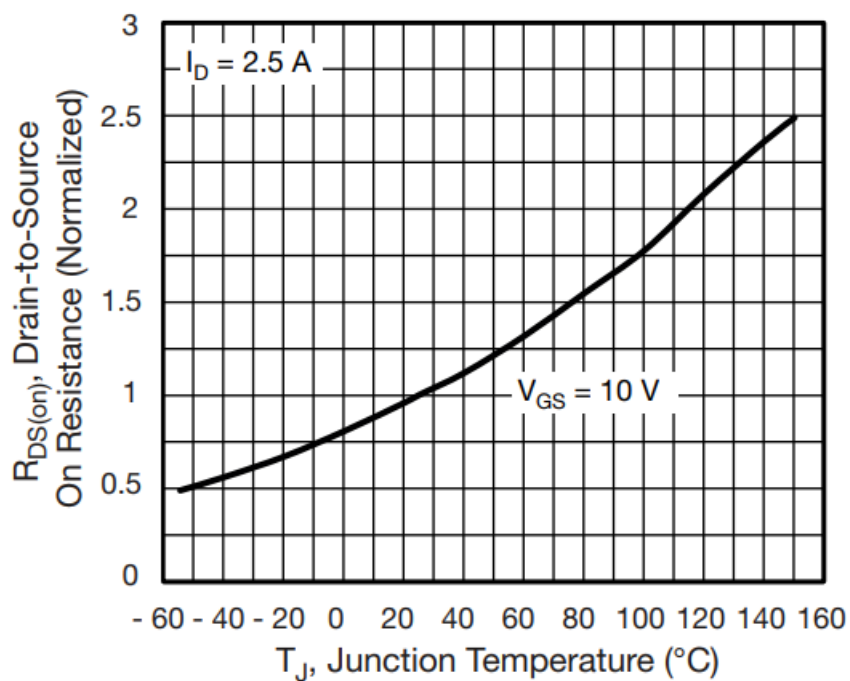


Fig. 4 - Normalized On-Resistance vs. Temperature

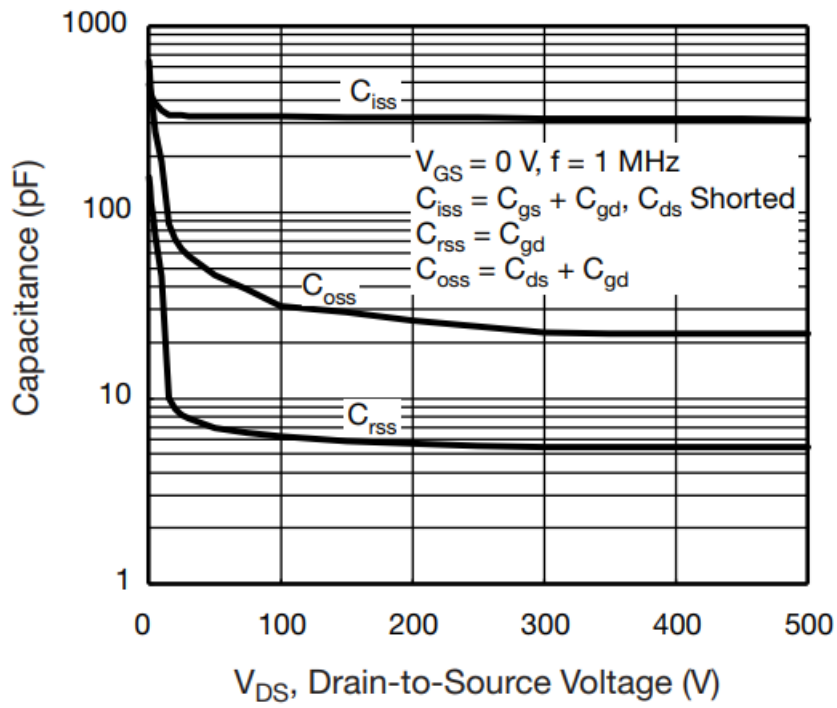


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

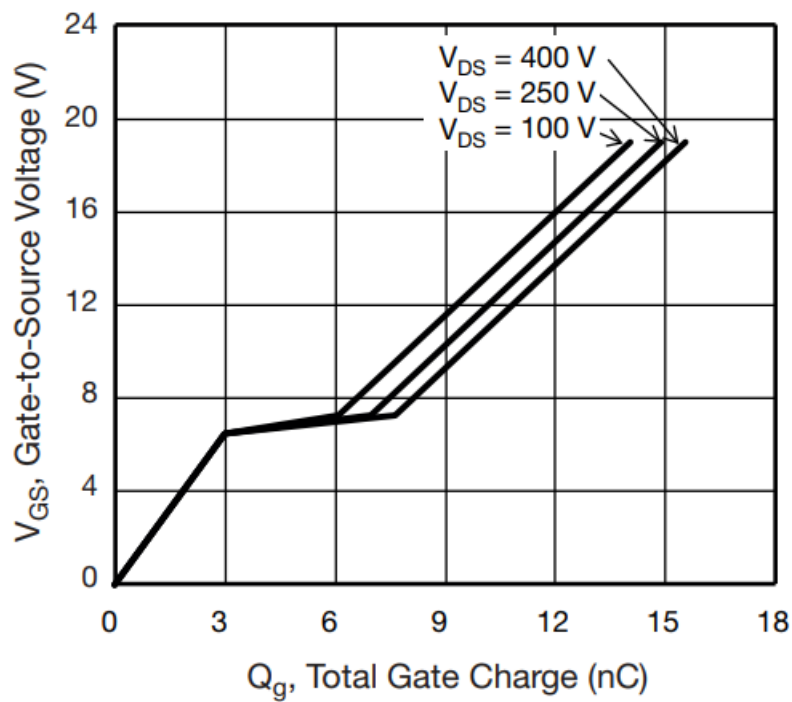


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

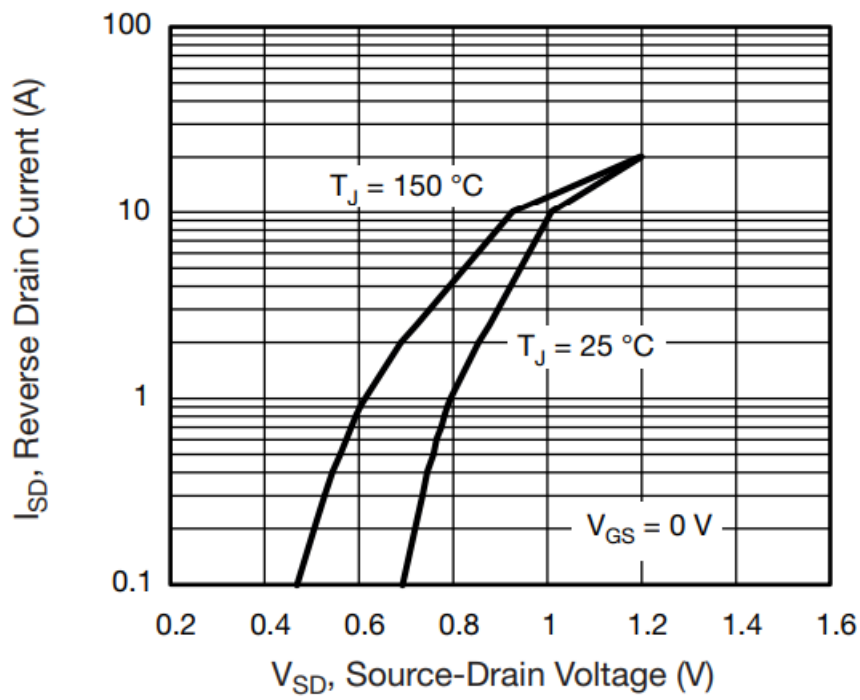


Fig. 7 - Typical Source-Drain Diode Forward Voltage

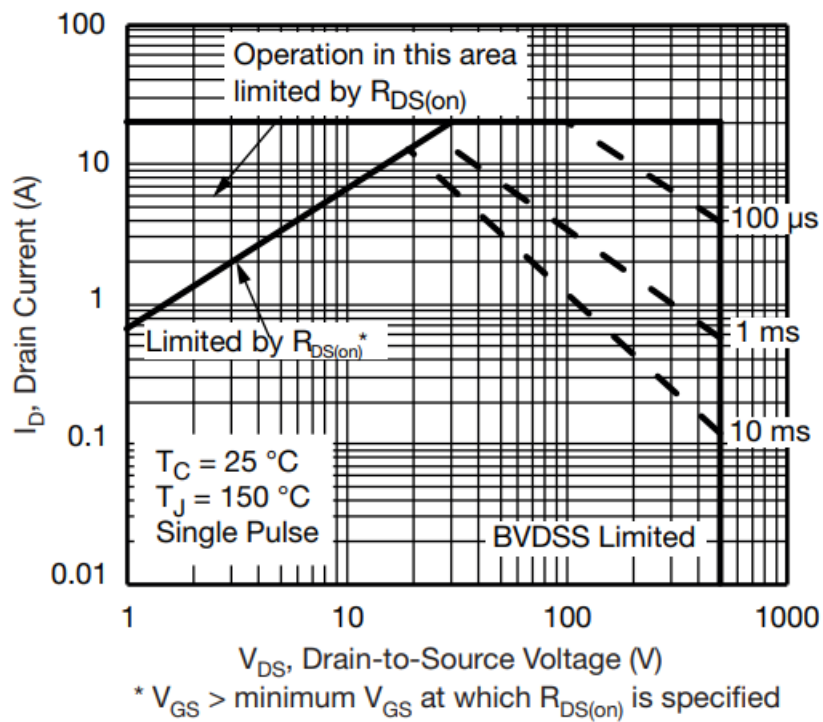


Fig. 8 - Maximum Safe Operating Area

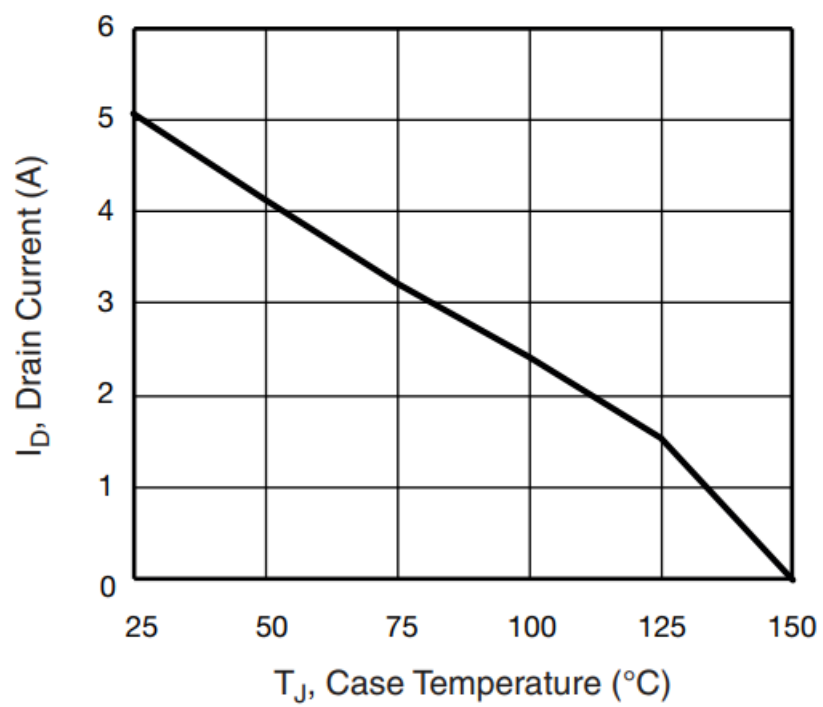


Fig. 9 - Maximum Drain Current vs. Case Temperature

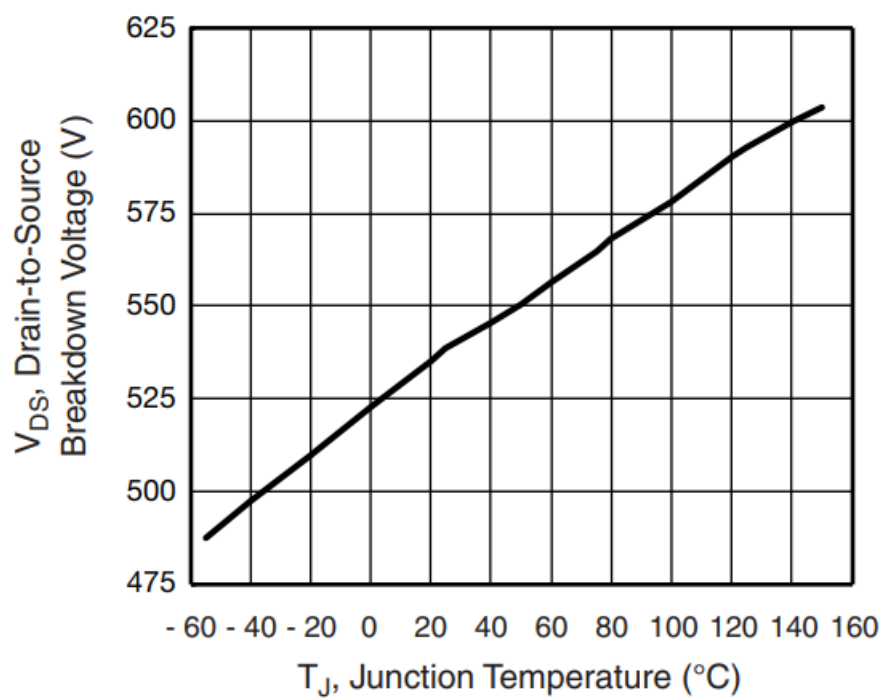


Fig. 10 - Typical Drain-to-Source Voltage vs. Temperature

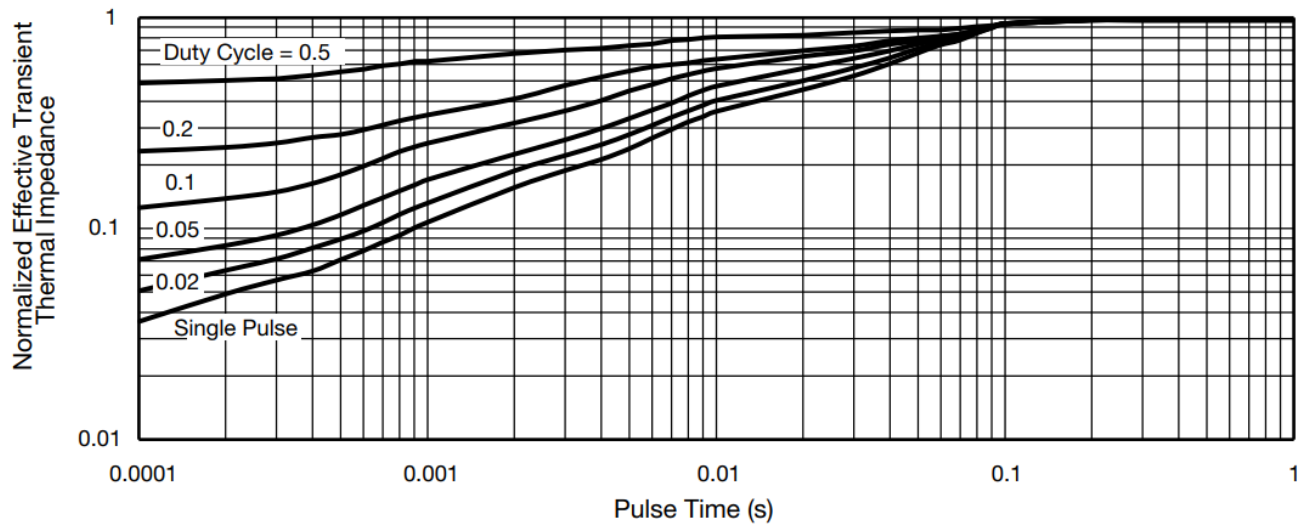


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

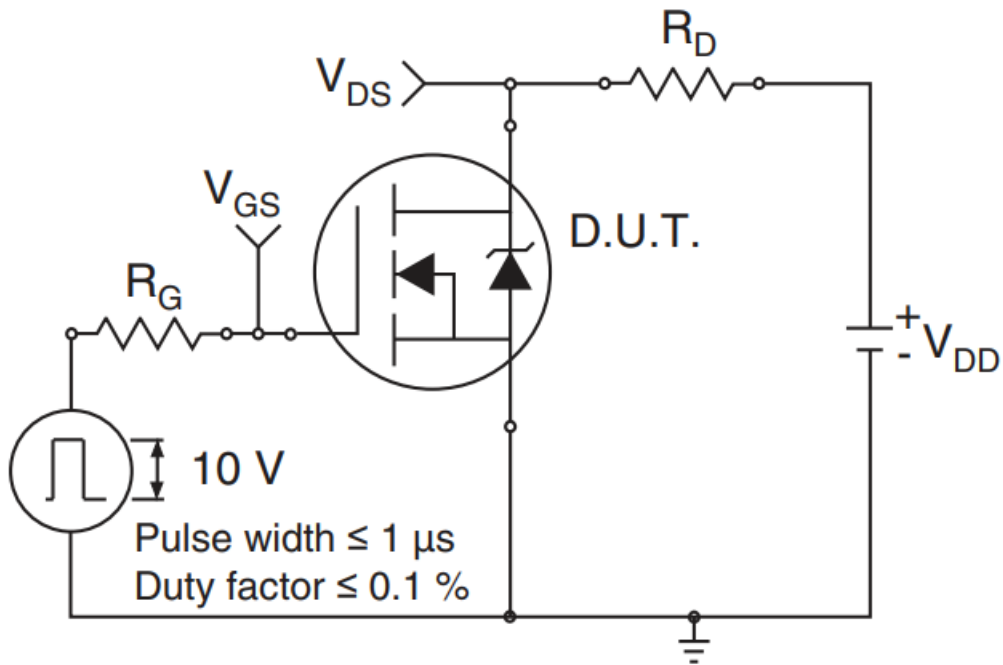


Fig. 12 - Switching Time Test Circuit

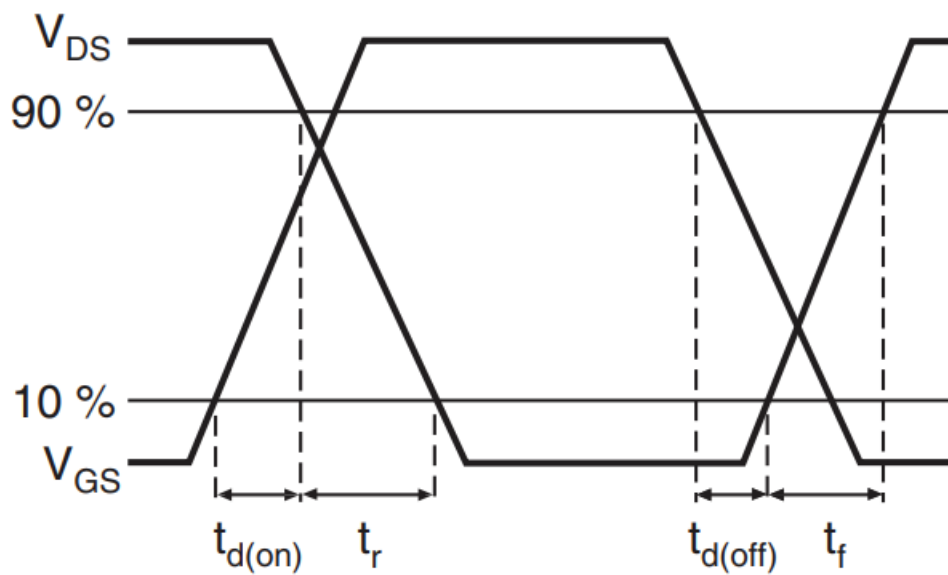


Fig. 13 - Switching Time Waveforms

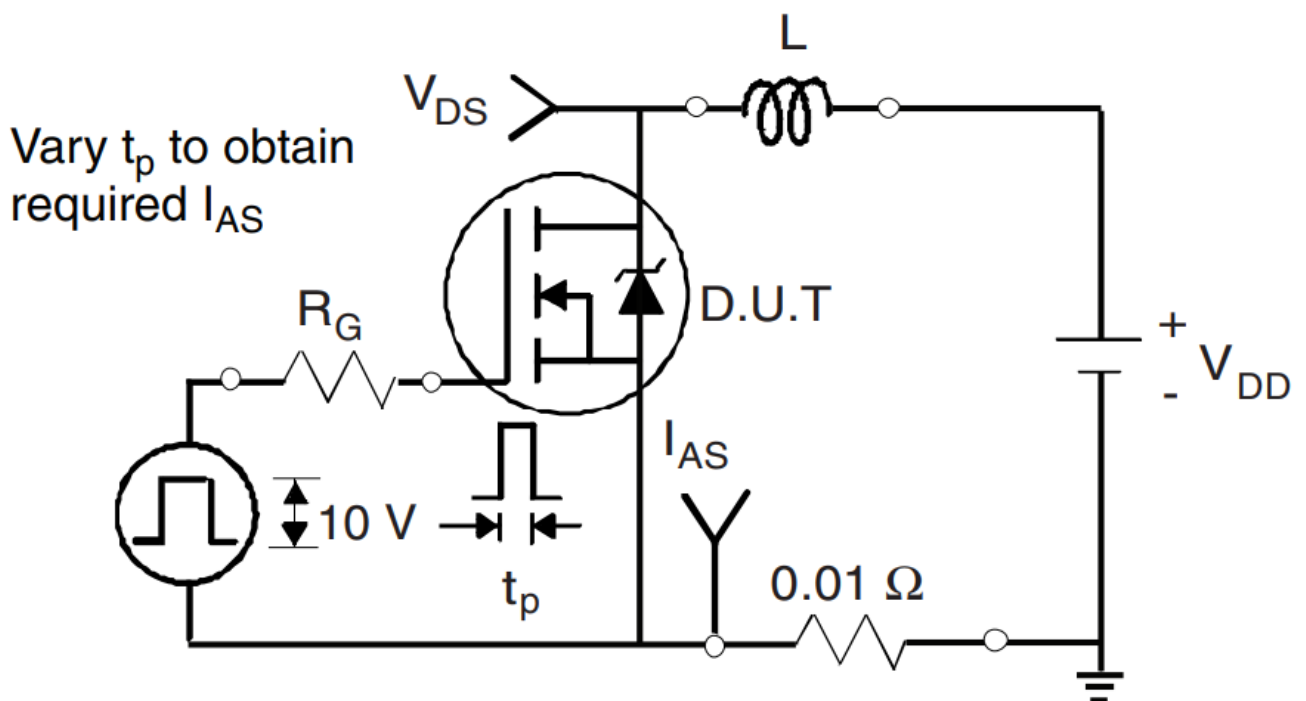


Fig. 14 - Unclamped Inductive Test Circuit

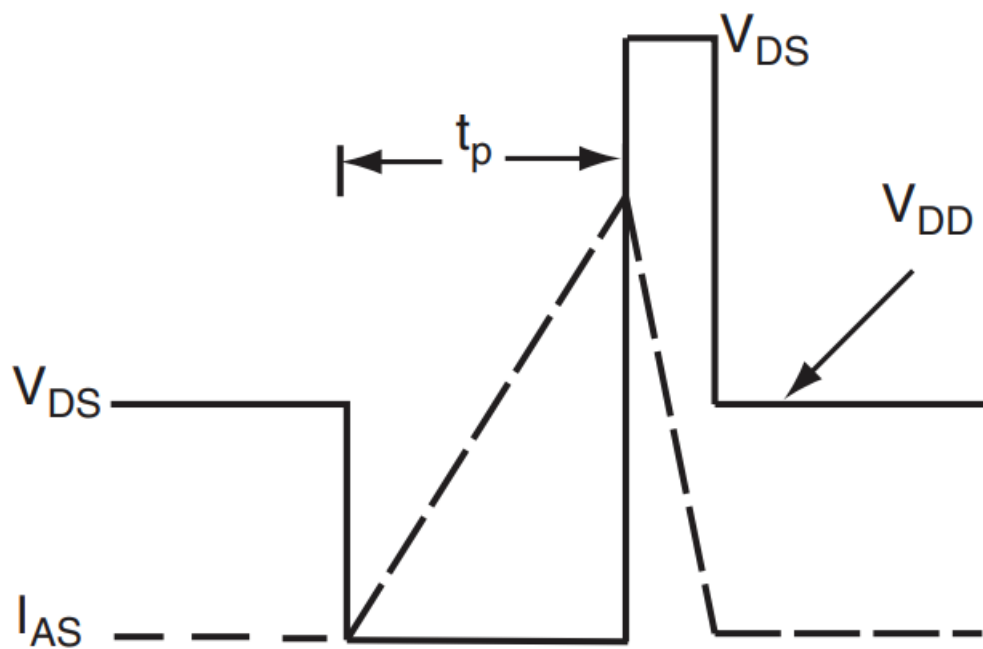


Fig. 15 - Unclamped Inductive Waveforms

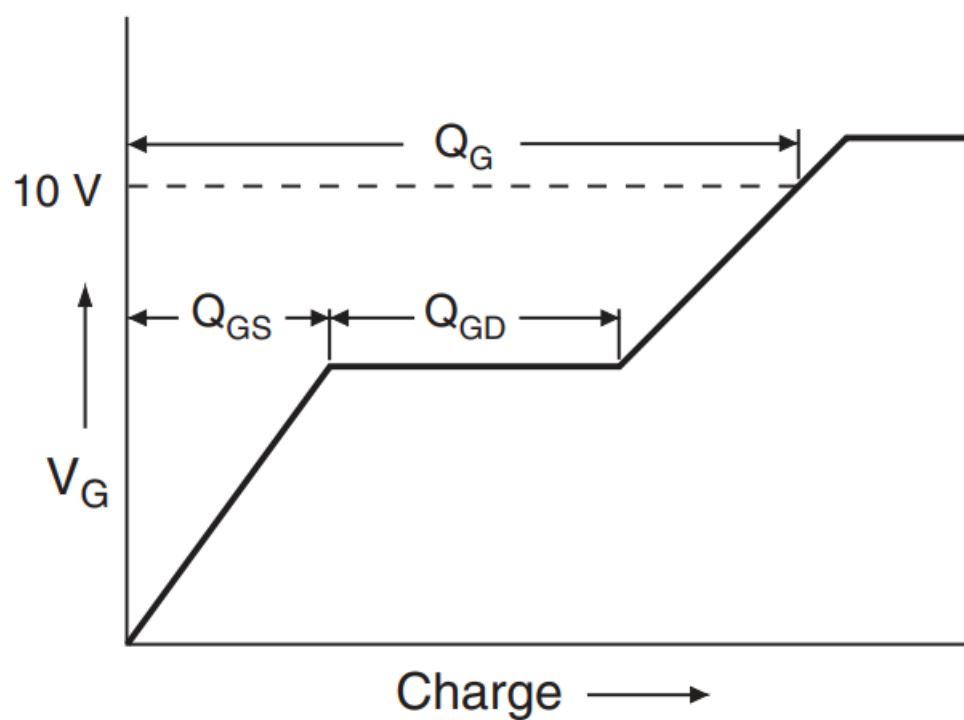


Fig. 16 - Basic Gate Charge Waveform

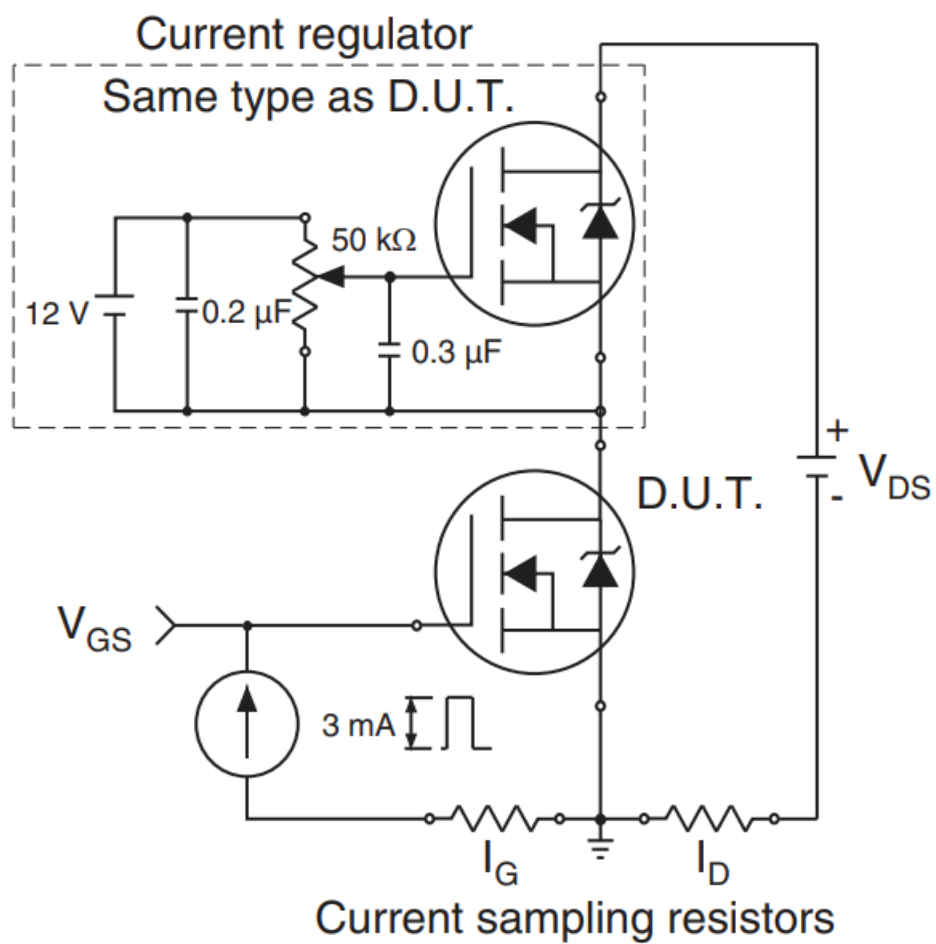
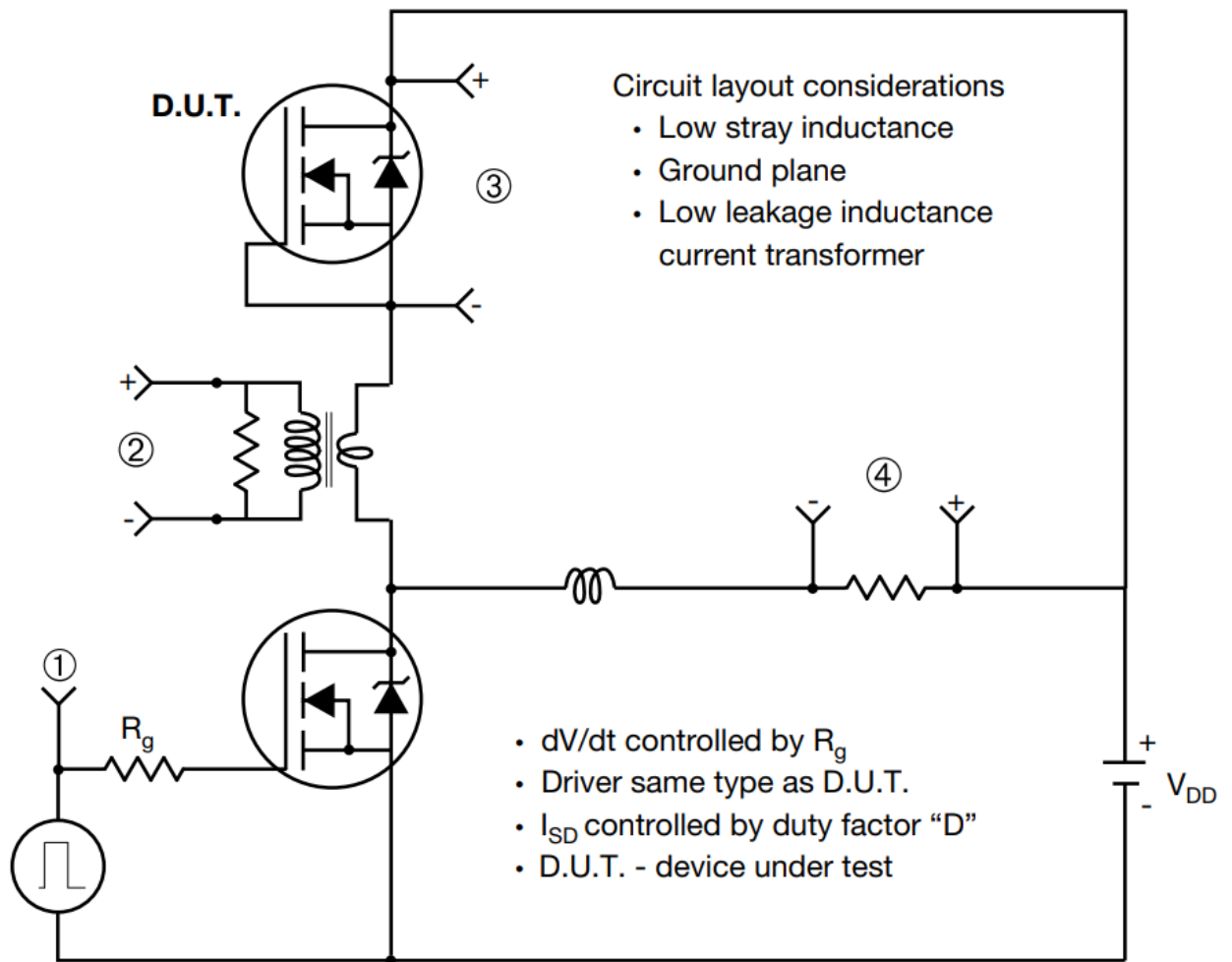
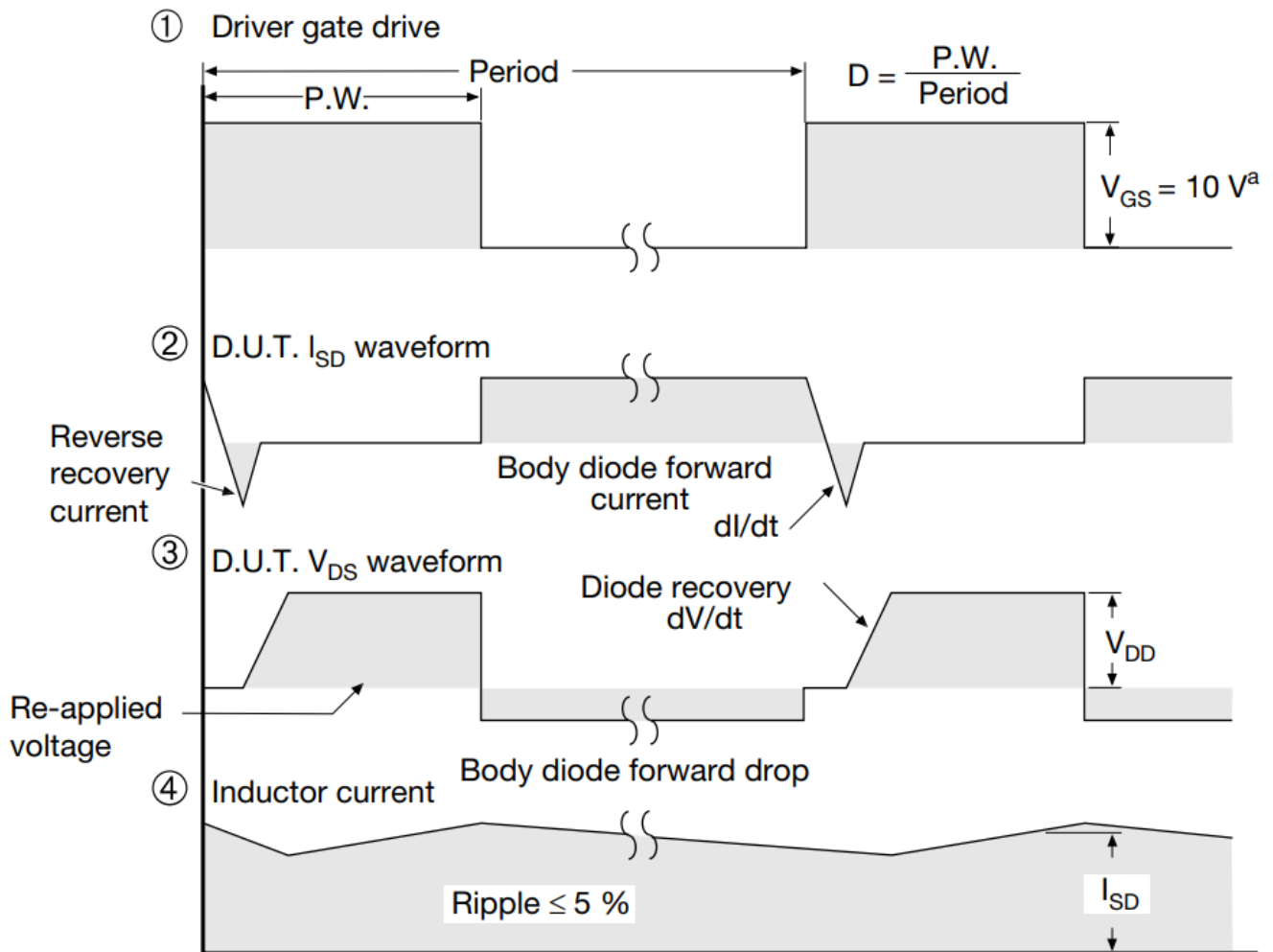


Fig. 17 - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit





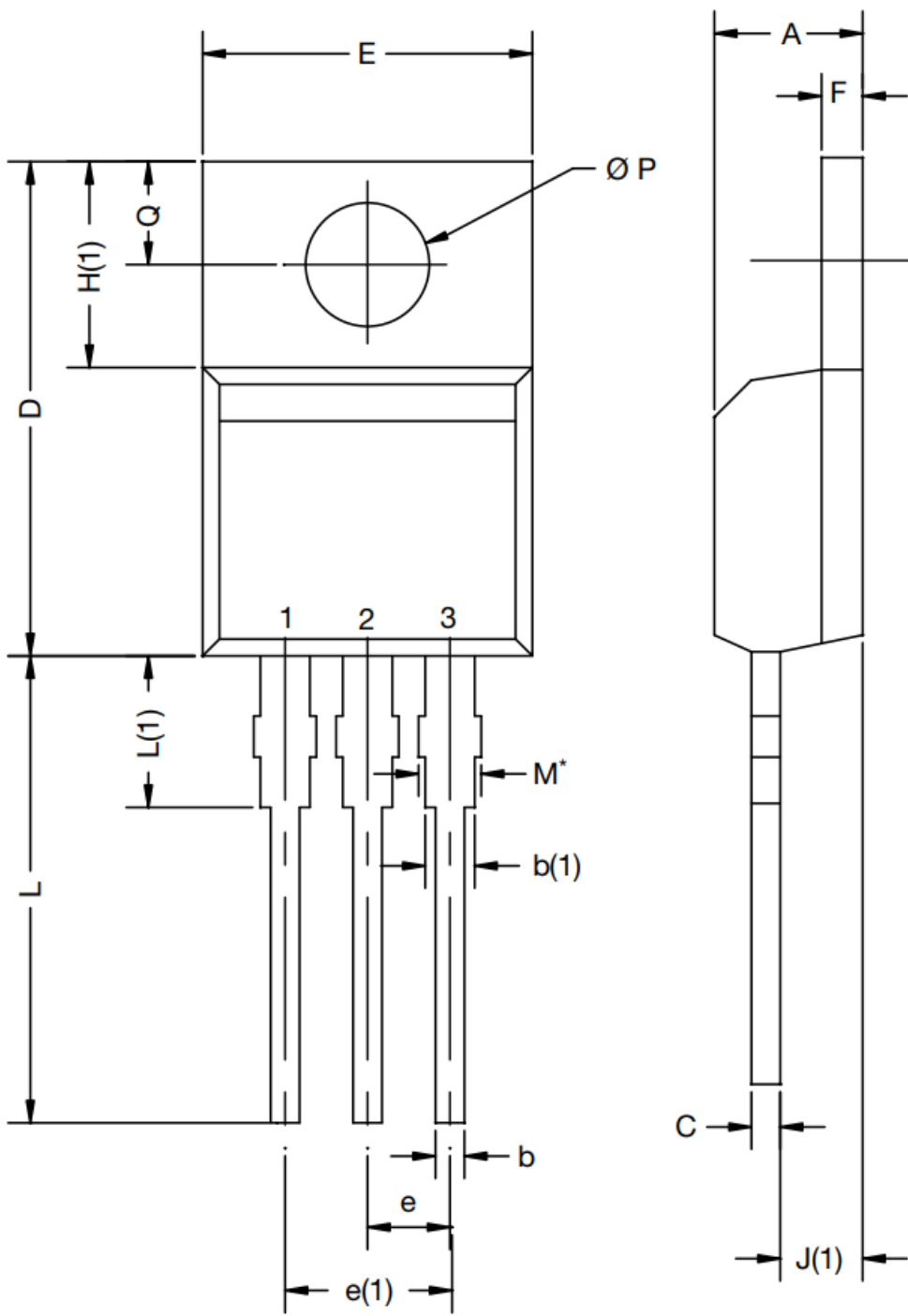
Note

a. $V_{GS} = 5 \text{ V}$ for logic level devices

Fig. 18 - For N-Channel

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Package Information



DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
Ø P	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118
ECN: E21-0621-Rev. D, 04-Nov-2021 DWG: 6031				

Note

- M* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM

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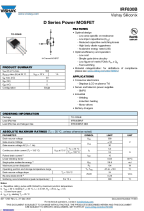
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References

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